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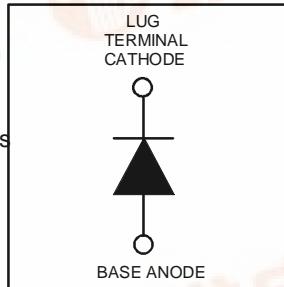
HFA105NH60R

HEXFRED™

Ultrafast, Soft Recovery Diode

Features

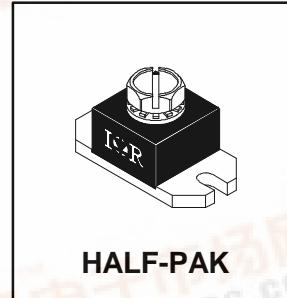
- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters



$V_R = 600V$
$V_F = 1.5V$
$Q_{rr}^* = 1200nC$
$di_{(rec)M}/dt^* = 240A/\mu s$
* 125°C

Description

HEXFRED™ diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

**Absolute Maximum Ratings**

	Parameter	Max.	Units
V_R	Cathode-to-Anode Voltage	600	V
$I_F @ T_C = 25^\circ C$	Continuous Forward Current	147	A
$I_F @ T_C = 100^\circ C$	Continuous Forward Current	72	
I_{FSM}	Single Pulse Forward Current ①	600	
I_{AS}	Maximum Single Pulse Avalanche Current ②	2.0	
E_{AS}	Non-Repetitive Avalanche Energy ②	220	μJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	379	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	152	
T_J	Operating Junction and		
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ C$

Thermal - Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case, Single	—	—	0.33	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat , Greased Surface	—	0.15	—	K/W
Wt	Weight	—	26 (0.9)	—	g (oz)
	Mounting Torque	15 (1.7)	—	25 (2.8)	lbf-in
	Terminal Torque	20 (2.2)	—	40 (4.4)	(N•m)

Note: ① Limited by junction temperature

② $L = 100\mu H$, duty cycle limited by max T_J

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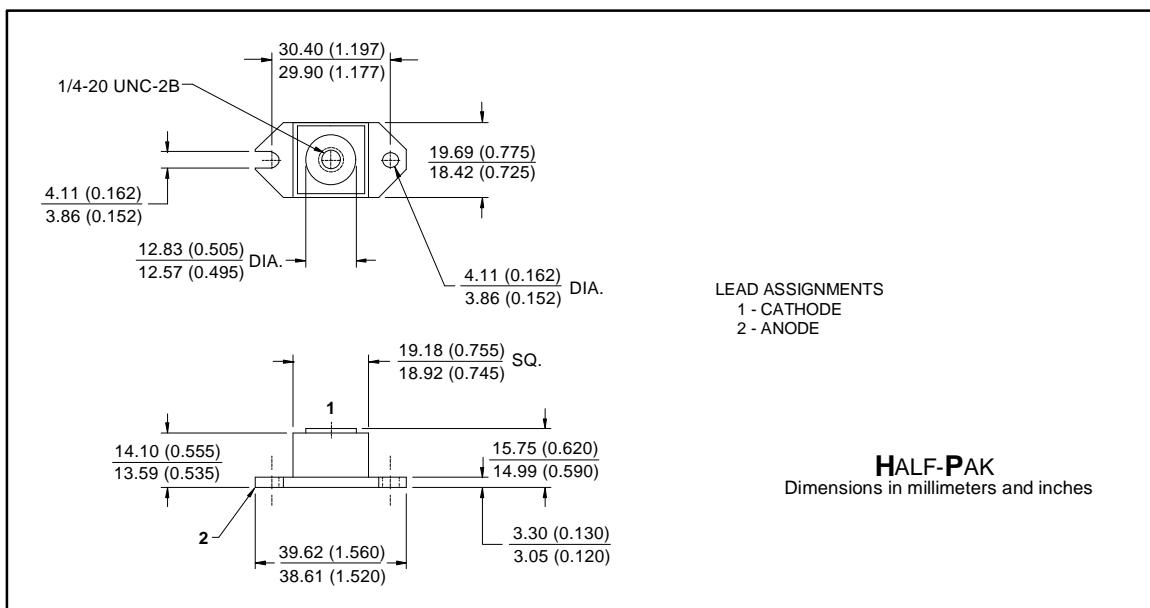


Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
V_{BR}	Cathode Anode Breakdown Voltage	600	—	—	V	$I_R = 100\mu\text{A}$
V_{FM}	Max Forward Voltage	—	1.3	1.5	V	$I_F = 105\text{A}$
			1.5	1.7		$I_F = 210\text{A}$
			1.2	1.4		$I_F = 105\text{A}, T_J = 125^\circ\text{C}$
I_{RM}	Max Reverse Leakage Current	6.0	30	μA	$V_R = V_R \text{ Rated}$	
			1.5	6.0		$T_J = 125^\circ\text{C}, V_R = 480\text{V}$
C_T	Junction Capacitance	—	200	300	pF	$V_R = 200\text{V}$
L_s	Series Inductance	—	6.0	—	nH	From top of terminal hole to mounting plane

Dynamic Recovery Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
t_{rr}	Reverse Recovery Time	—	35	—	ns	$I_F = 1.0\text{A}, dI/dt = 200\text{A}/\mu\text{s}, V_R = 30\text{V}$
			90	140		$T_J = 25^\circ\text{C}$
			160	240		$T_J = 125^\circ\text{C}$
I_{RRM1}	Peak Recovery Current	—	10	18	A	$T_J = 25^\circ\text{C}$
			15	30		$T_J = 125^\circ\text{C}$
Q_{rr1}	Reverse Recovery Charge	—	450	1300	nC	$T_J = 25^\circ\text{C}$
			1200	3600		$T_J = 125^\circ\text{C}$
$dI_{(rec)M}/dt_1$	Peak Rate of Fall of Recovery Current During t_b	—	310	—	A/ μs	$T_J = 25^\circ\text{C}$
			240	—		$T_J = 125^\circ\text{C}$



IOR

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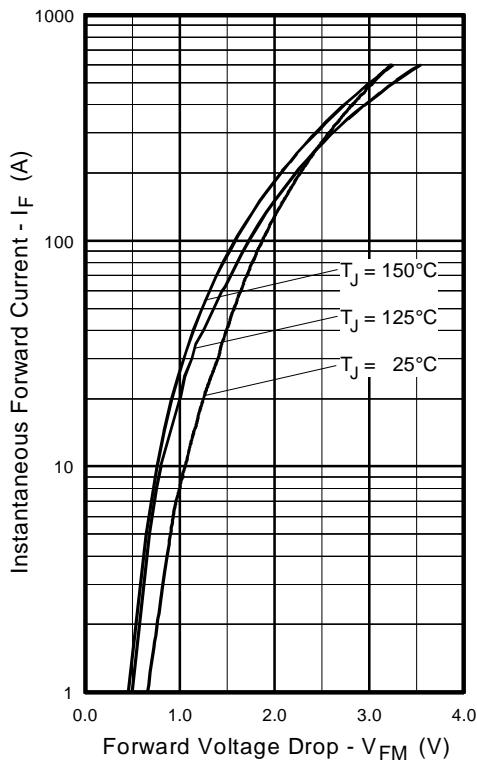


Fig. 1 - Maximum Forward Voltage Drop
vs. Instantaneous Forward Current

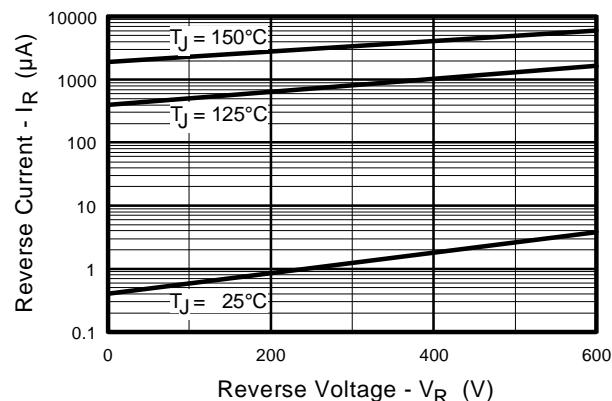


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

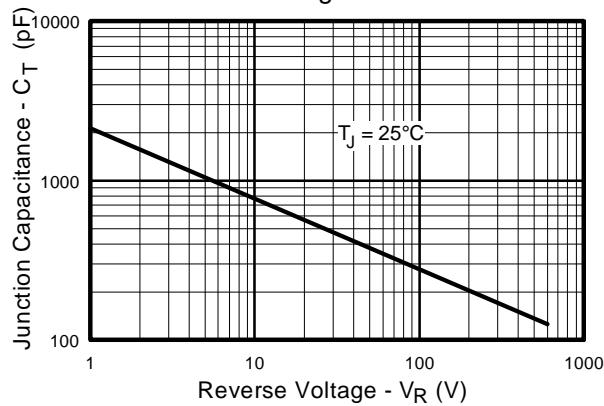


Fig. 3 - Typical Junction Capacitance vs.
Reverse Voltage

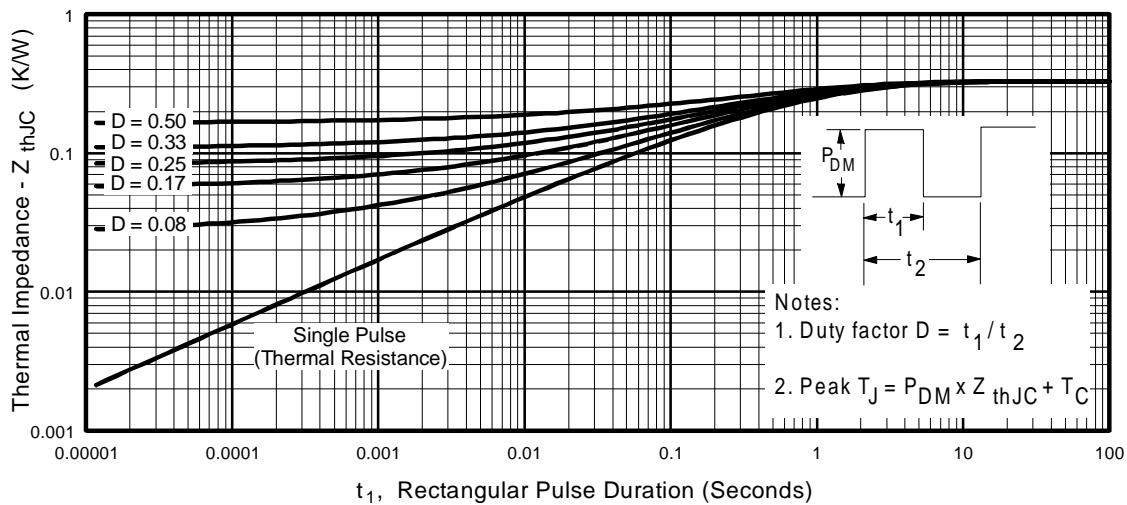


Fig. 4 - Maximum Thermal Impedance Z_{thjc} Characteristics

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ICR

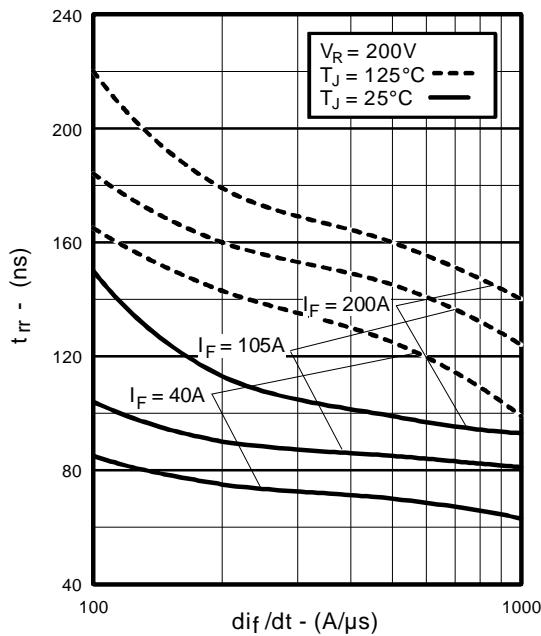


Fig. 5 - Typical Reverse Recovery vs. dI/dt

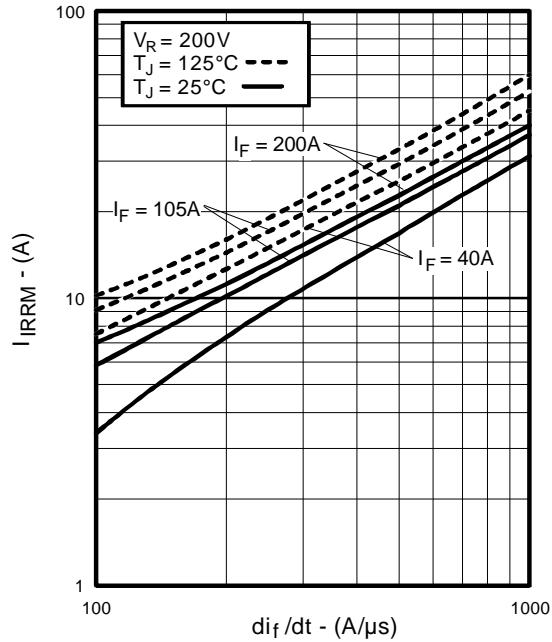


Fig. 6 - Typical Recovery Current vs. dI/dt

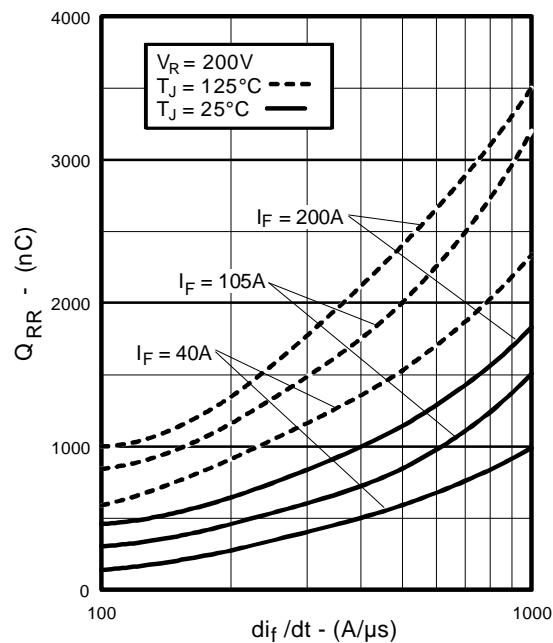


Fig. 7 - Typical Stored Charge vs. dI/dt

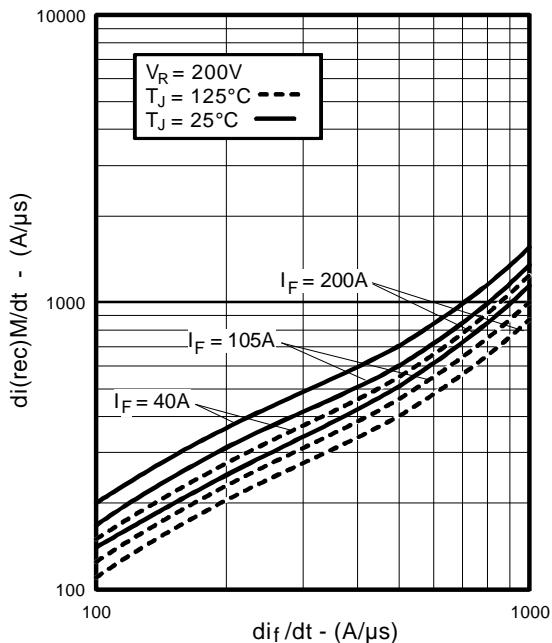
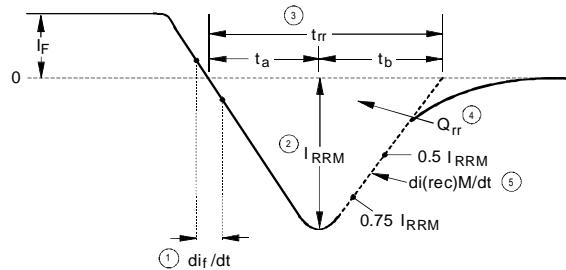
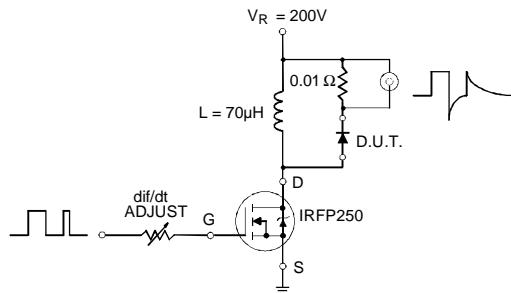


Fig. 8 - Typical $dI_{rec}M/dt$ vs. dI/dt

REVERSE RECOVERY CIRCUIT



1. $\frac{di}{dt}$ - Rate of change of current through zero crossing

2. I_{RRM} - Peak reverse recovery current

3. t_{rr} - Reverse recovery time measured from zero crossing point of negative going i_t to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current

4. Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

5. $\frac{di_{(rec)}M}{dt}$ - Peak rate of change of current during t_{rr} portion of t_{rr}

Fig. 9 - Reverse Recovery Parameter Test Circuit

Fig. 10 - Reverse Recovery Waveform and Definitions

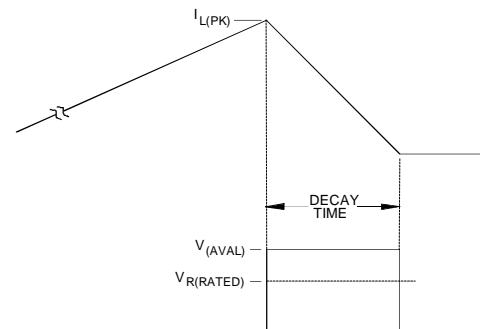
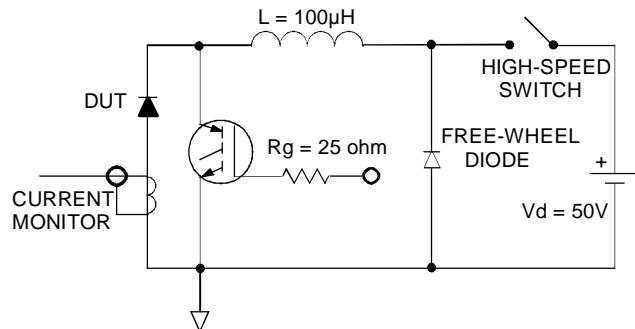


Fig. 11 - Avalanche Test Circuit and Waveforms